What is claimed is:

1. A method of fabricating a substrate for a display device, comprising the steps of:

forming a photosensitive organic material layer on or over a transparent plate, the layer being divided into a display section and a terminal section located outside the display section, and the layer having a first thickness in the display section and a second thickness different from the first thickness in the terminal section; and

exposing the layer to exposing light in such a way that the layer in the display section is exposed at a first exposure value according to the first thickness and the layer in the terminal section is exposed at a second exposure value according to the second thickness.

2. A method of fabricating a substrate for a display device, comprising the steps of:

forming a photosensitive organic material layer on or over a transparent plate, the layer being divided into a display section and a terminal section located outside the display section, and the layer having a first thickness in the display section and a second thickness different from the first thickness in the terminal section;

exposing the layer in the display section and the terminal section to exposing light at a first exposure value according to a relatively smaller one of the first thickness and the second thickness; and

selectively exposing part of the layer having a relatively larger one of the first thickness and the second thickness to exposing light at a second exposure value.

3. A method of fabricating a LCD device, comprising the steps of:

forming a photosensitive organic material layer on or over a transparent plate, the photosensitive organic material layer being divided into a display section and a terminal section located outside the display section, the display section including a reflection region and a contact-hole area, and the photosensitive organic material layer having a first thickness in the reflection region, a second thickness different from the first thickness in the contact-hole area, and a third thickness different from the first and second thicknesses in the terminal section;

exposing the photosensitive organic material layer to exposing light in such a way that the photosensitive organic material layer in the reflection region is exposed at a first exposure value according to the first thickness, the

photosensitive organic material layer in the contact-hole area is exposed at a second exposure value according to the second thickness, and the photosensitive organic material layer in the terminal section is exposed at a third exposure value according to the third thickness;

developing the photosensitive organic material layer exposed, thereby forming a first substrate;

forming a second substrate; and

coupling the first substrate and the second substrate with each other in such a way as to sandwich a liquid-crystal layer therebetween.

4. The method according to claim 3, wherein in the step of exposing the photosensitive organic material layer, the contact-hole area and the terminal section are exposed to the light in one shot at the second exposure value, and the terminal section is again exposed to the light in another shot at a difference between the second exposure value and the third exposure value.

5. The method according to claim 3, wherein in the step of exposing the photosensitive organic material layer, the contact-hole area and the terminal section are respectively exposed to the light in one shot at the second and third

exposure values using a half-tone mask.

6. The method according to claim 3, wherein in the step of exposing the photosensitive organic material layer, the reflection region, the contact-hole area, and the terminal section are respectively exposed to the light in separate shots using different masks;

and wherein a blind of a stepper used is kept fully open.

7. The method according to claim 3, wherein in the step of exposing the photosensitive organic material layer, the reflection region, the contact-hole area, and the terminal section are respectively exposed to the light using different masks;

and wherein each of the masks has a three-layer structure comprising a light-shielding layer for an exposing pattern, and two anti-reflection layers located at each side of the light-shielding layer.

8. A method of fabricating a LCD device, comprising the steps of:

forming a photosensitive organic material layer on or over a transparent plate, the photosensitive organic material

layer being divided into a display section and a terminal section located outside the display section, the display section including a reflection region and a transmission region, and the photosensitive organic material layer having a first thickness in the reflection region, a second thickness different from the first thickness in the transmission region, and a third thickness different from the first and second thicknesses in the terminal section;

exposing the photosensitive organic material layer to exposing light in such a way that the photosensitive organic material layer in the reflection region is exposed at a first exposure value according to the first thickness, the photosensitive organic material layer in the transmission region is exposed at a second exposure value according to the second thickness, and the photosensitive organic material layer in the terminal section is exposed at a third exposure value according to the third thickness;

developing the photosensitive organic material layer exposed, thereby forming a first substrate;

forming a second substrate; and

coupling the first substrate and the second substrate with each other in such a way as to sandwich a liquid-crystal layer therebetween.

9. The method according to claim 8, wherein in the step of exposing the photosensitive organic material layer, the transmission region and the terminal section are exposed to the light in one shot at the second exposure value, and the terminal section is again exposed to the light in another shot at a difference between the second exposure value and the third exposure value.

10. The method according to claim 8, wherein in the step of exposing the photosensitive organic material layer, the transmission region and the terminal section are respectively exposed to the light in one shot at the second and third exposure values using a half-tone mask.

11. The method according to claim 8, wherein in the step of exposing the photosensitive organic material layer, the reflection region, the transmission region, and the terminal section are respectively exposed to the light in separate shots using different masks;

and wherein a blind of a stepper used is kept fully open.

12. The method according to claim 8, wherein in the step of exposing the photosensitive organic material layer, the

reflection region, the transmission region, and the terminal section are respectively exposed to the light using different masks;

and wherein each of the masks has a three-layer structure comprising a light-shielding layer for an exposing pattern, and two anti-reflection layers located at each side of the light-shielding layer.

13. A semi-transmissive type LCD device comprising:

a first substrate comprising a transparent plate, switching elements formed on the plate, an inequalized photosensitive organic material layer formed on the plate, and a reflection layer formed on the photosensitive organic material layer;

the first substrate being divided into a reflection region and a transmission region in each pixel area, and the photosensitive organic material layer being located in the reflection region;

a light-shielding layer formed on the first substrate in such a way as to be located behind the photosensitive organic material layer;

the light-shielding layer covering a neighborhood of a boundary between the reflection region and the transmission region, an edge of the photosensitive organic material layer

being included in the neighborhood;

a second substrate coupled with the first substrate; and

a liquid-crystal layer sandwiched by the first and second substrates.

14. The device according to the claim 13, wherein the neighborhood covered with the light-shielding layer has an inward distance and an outward distance along the first substrate from the edge of the photosensitive organic resin layer;

and wherein each of the inward distance and the outward distance is equal to 5 μm or greater.

15. The device according to the claim 13, wherein the light-shielding layer is located in a same level as scanning lines or signal lines formed on or over the first substrate.

16. The device according to the claim 13, wherein the light-shielding layer is formed by a storage electrode formed on the first substrate.